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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP: 2827

32692

Customer Number

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Patent
Case No.: 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600

Group Art Unit: 2827

Filed: October 17, 2000

Examiner: Luan C. Thai

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED
SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDINGPlease enter
LTAMENDMENT AND RESPONSE UNDER 37 CFR § 1.116Mail Stop AP
Commissioner for Patents
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CERTIFICATE OF TRANSMISSION	
To Fax No.: 703-872-9306	
I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office on:	
18 May 2004 Date	<i>Susan P. Gurnatz</i> Signed By: Susan P. Gurnatz or Dean M. Harris

Dear Sir:

This is in response to the outstanding Office Action, mailed March 25, 2004, in the above-identified application.

This response is filed within two months of said mailing date.

This Amendment is believed to be timely submitted. It is believed that no fee is due; however, in the event a fee is required, please charge the fee to Deposit Account No. 13-3723.